

**STACKED MULTI-COMPONENT INTEGRATED  
CIRCUIT MICROPROCESSOR**

ABSTRACT OF THE DISCLOSURE

An apparatus and method for fabricating a microprocessor comprising a first chip (12) having an active face (30) including a central processing unit and a second chip (14) having an active face (32) electrically connected to the active face of the first chip (12), wherein the second chip (14) provides added functionality to the central processing unit of the first chip (12) and wherein the electrical connections (16, 18) are through bonding layers (28) that are in contact with the metalization 26 on the first and second chips (12, 14), is disclosed.

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